# Monthly LabAdviser update: 13/5 2013

|  |  |  |
| --- | --- | --- |
| Updated Subject  | Contributer | Link to the update pages |
| **Process2Share**Link to a Master Project  | Thomas Lehrmann Christiansen @nanotech | [http://process2share.danchip.dtu.dk/index.php/Projects,\_Theses\_and\_Papers/Master\_Projects](http://process2share.danchip.dtu.dk/index.php/Projects%2C_Theses_and_Papers/Master_Projects) |
| **TEOS furnace**Some results have been added. | Pernille V. Larsen @danchip | <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_TEOS/Deposition_of_TEOS_using_LPCVD#Expected_results_when_using_the_standard_recipe_on_the_LPCVD_nitride_furnace> |
| **KLA-Tencor Surfscan**New machine to count particles on unpatterned surface. Particles size 0.1 µm to 3 µm.More process relevant stuff will come in later.  | Mikkel D. Mar @danchip | <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Characterization/KLA-Tencor_Surfscan_6420> |
| **Die Bonder and Flip-chip Bonder**Updated equipment page | Jesper Hanberg@ danchip | [Die Bonder (eutectic metal)](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Back-end_processing/Die_Bonder)[Flip-chip Bonder (glue)](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Back-end_processing/Die_Bonder#Flip-chip_bonder_.28glue_attachment.29) |
| **TPT Wire bonder and Ball Wire bonder**Updated equipment page | Jesper Hanberg@ danchip | [TPT Wire Bonder](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Back-end_processing/Wire_Bonder)[Ball Wire Bonder](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Back-end_processing/Wire_Bonder#Ball_Wire_Bonder_K.26S_4524) |
| **Deposition of Germanium**New page on how to deposit Germanium at Danchip. | Katharina Nilson @danchip | <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Germanium> |
| **Etching SiO2 with AOE**Etch rates in TEOS and PECVD oxide | Berit G. Herstrøm @ danchip | <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Etching_of_Silicon_Oxide/SiO2_etch_using_AOE#Etching_of_micro_structures_in_Silicon_Oxide_with_photoresist_as_masking_material> |
| **Etching fused silica with the AOE**With resist mask and with Psi mask | Berit G. Herstrøm @ danchip | <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Etching_of_Bulk_Glass/AOE_etching_of_fused_silica> |
| **Etch**Updated comparison pages for all material to be etched | Berit G. Herstrøm @ danchip | [Etching\_of\_Aluminium](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Etching_of_Aluminium)[Etching\_of\_Chromium](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Etching_of_Chromium)[Etching\_of\_Titanium](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Etching_of_Titanium)[Etching\_of\_Gold](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Etching_of_Gold)[Etching\_of\_Platinum](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Etching_of_Platinum)[Etching\_of\_Polymer](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Etching_of_Polymer)[Etching\_of\_Silicon](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Etching_of_Silicon)[Etching\_of\_Silicon\_Nitride](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Etching_of_Silicon_Nitride)[Etching\_of\_Silicon\_Oxide](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Etching_of_Silicon_Oxide)[Etching\_of\_Bulk\_Glass](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Etching_of_Bulk_Glass) |